

Lead Forming of Axial-Lead Packages

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APPLICATION NOTE

When bending the leads of an Axial-Lead package, several basic rules should be followed to prevent mechanical damage to the package and die. Improper bending of the leads can result in degradation of the electrical characteristics and/or reliability of the device.

Lead Bending Rules:

1. The leads should be securely clamped between the bending point and the plastic body. The minimum distance (D) from the plastic body is 1.5 times the typical lead diameter. The preferable distance is at least 2 times the typical lead diameter.
2. Do not clamp on the plastic body.
3. The forming tool should not damage the leads or the plastic body.
4. The radius of the bends should not be less than the lead diameter.
5. Avoid twisting or axial motion of the leads with respect to the plastic body.
6. Bending of the leads should be performed only once.
7. The bend angle should not exceed 90 degrees.

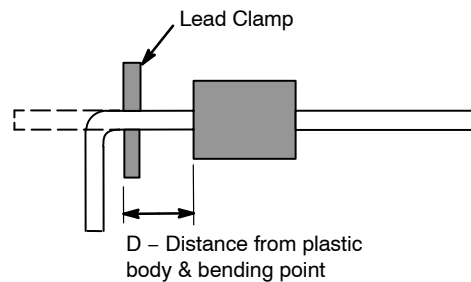



Figure 1.

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